

= 170 A

= 600 V

IGBT Modules Sixpack

Short Circuit SOA Capability Square RBSOA

Preliminary data

IGBTs





See outline drawing for pin arrangement

€NPT IGBT technology €low saturation voltage

V_{CE(sat) typ.} **= 2.0 V**

Features

C25 **V**_{CES}

Symbol	Conditions	Maximum Rating	 €NPT IGBT technology s €low saturation voltage
V _{CES}	$T_{vJ} = 25^{\circ}C$ to $150^{\circ}C$	600	V €low switching losses V €switching frequency up to 30 kHz
V _{ges}		± 20	✓ €square RBSOA, no latch up €high short circuit capability
I _{C25} I _{C80}	$T_{c} = 25^{\circ}C$ $T_{c} = 80^{\circ}C$	170 115	A €positive temperature coefficient fo A easy parallelling
RBSOA	$V_{GE} = \pm 15 \text{ V}; \text{ R}_{G} = 1.5 \Omega; \text{ T}_{VJ} = 125^{\circ}\text{C}$ Clamped inductive load; L = 100 µH	$I_{CM} = 300$ $V_{CEK} \le V_{CES}$	A €MOS input, voltage controlled €ultra fast free wheeling diodes €solderable pins for PCB mounting
t _{sc} (SCSOA)	$V_{CE} = V_{CES}; V_{GE} = \pm 15 \text{ V}; \text{ R}_{G} = 1.5 \Omega; \text{ T}_{VJ} = 100 \text{ non-repetitive}$	125°C 10 µ	€package with copper base plate
P _{tot}	$T_c = 25^{\circ}C$	515 V	 Advantages V €space savings Graduard protection circuits

S

Symbol	Conditions (T	_{vJ} = 25°C, unle	Characteristic Values , unless otherwise specified)				
		mi	n. ty	′p. r	nax.		
V _{CE(sat)}	$I_c = 150 \text{ A}; V_{ge} = 15 \text{ V}; T_{vJ} = 25$ $T_{vJ} = 125$	S°C S°C	2. 2.	.0 .3	2.5	V V	
$V_{GE(th)}$	$I_c = 3 \text{ mA}; V_{GE} = V_{CE}$	4.	5		6.5	V	
I _{CES}	$V_{CE} = V_{CES}; V_{GE} = 0 V; T_{VJ} = 25^{\circ} T_{VJ} = 125^{\circ} T_{VJ}$	0	1.	.1	1.5	mA mA	
I _{GES}	$V_{ce} = 0 \text{ V}; V_{ge} = \pm 20 \text{ V}$				400	nA	
$t_{d(on)}$ t_r $t_{d(off)}$ t_f E_{on} E_{off}	$\left\{ \begin{array}{l} \text{Inductive load, } T_{\text{VJ}} = 125^{\circ}\text{C} \\ \text{V}_{\text{CE}} = 300 \text{ V; } \text{I}_{\text{C}} = 150 \text{ A} \\ \text{V}_{\text{GE}} = \pm 15 \text{ V; } \text{R}_{\text{G}} = 1.5 \Omega \end{array} \right.$		12 3 22 3 2. 4.	25 90 25 95 95 95 95 95 95 95 95 95 95 95 95 95		ns ns ns mJ mJ	
C _{ies} Q _{Gon}	$V_{ce} = 25 \text{ V}; V_{ge} = 0 \text{ V}; \text{ f} = 1 \text{ MHz}$ $V_{ce} = 300 \text{ V}; V_{ge} = 15 \text{ V}; \text{ I}_{c} = 150$	A	6. 52	.5 20		nF nC	
R _{th-IC}	(per IGBT)			0	0.24	K/W	

€package with copper base plate **Advantages** €space savings €reduced protection circuits €package designed for wave soldering

Typical Applications

€AC motor control €AC servo and robot drives €power supplies

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Diodes		Equivalent Circuits for Simulation			
Symbol	Conditions	Maximu	m Rati	ngs	Conduction
F25	$T_c = 25^{\circ}C$	210	0	A	
F80	$T_c = 80 \text{ C}$	130	0		
Symbol	Conditions	aracteri	stic Va	lues	
	min.	typ.	max.		0_0
V _F	$I_{F} = 150 \text{ A}; V_{GE} = 0 \text{ V}; T_{VJ} = 25^{\circ}\text{C}$ $T_{VJ} = 125^{\circ}\text{C}$	1.9 1.4	2.0	V V	IGBT (typ. at $V_{GE} = 15 \text{ V}$; $T_J = 125^{\circ}\text{C}$) $V_0 = 1.1 \text{ V}$; $R_0 = 8 \text{ m}\Omega$
$\left\{ t_{rr}^{RM} \right\}$	$I_{_{F}} = 150 \text{ A}; di_{_{F}}/dt = -750 A/\mu \text{s}; T_{_{VJ}} = 125^{\circ}\text{C}$ $V_{_{R}} = 300 V; V_{_{GE}} = 0 V$	37 100		A ns	Free Wheeling Diode (typ. at $T_J = 125^{\circ}$ C) $V_0 = 1.1 V; R_0 = 2.25 m\Omega$
R _{thJC}	(per diode)		0.41	K/W	Thermal Response
Module					
Symbol	Conditions	Maximu	m Rati	nas	
	operating -	40+12	5	°C	
T _{JM}		+150	0	°C	
V		250	0 N	Va	IGBT (typ.) $C_{11} = 0.295 \cdot I/K^2 B_{11} = 0.176 K/W$
M.	$M_{\rm ISOL} \simeq 1 {\rm max}, 30/00 {\rm mz}$	3 - 4	6	Nm	$C_{th2} = 1.750 \text{ J/K}; R_{th2} = 0.064 \text{ K/W}$
					Free Wheeling Diode (typ.) $C_{1} = 0.21 \ VK \cdot B_{2} = 0.317 \ KW$
Symbol	Conditions Ch min.	aracteri: typ.	stic Va max.	llues	$C_{th1} = 0.275 M, R_{th1} = 0.507 KW$ $C_{th2} = 1.28 J/K; R_{th2} = 0.093 K/W$
R _{pin-chip}		1.8		mΩ	
d _s d _A	Creepage distance on surface 10 Strike distance in air 10			mm mm	
R _{thCH}	with heatsink compound	0.01		K/W	
Weight		300		g	Dimensions in mm (1 mm = 0.0394")
	122 +0.3		 		118,11
B		נ ק ר	2.0± 2,2		94,5 Ø 2,1/=6mm
11.5	x + 11.5	54 21	₽ ₽ ₽		
		38,33] 	
£. 2		34,52 30,71			
$\frac{62 + 0}{57,5 \pm 1}$ $\frac{57,5 \pm 1}{47}$		19,29 15,47		Dase,	plare convex over 97,5 mm before mounting
		[11,66] [0]	:	N	
				±0.0;	4.5 4.3
<u>¢ 5,5</u>		4,19	-		
	60.7 34.0 34.0 77.75 75.75 14.92 77.75 75.75 14.15			1.2 ± 0.0	
	4,5 20/2	für Version VI/MKIA8T			
					I

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25.163.2453.0	25.163.4253.0	25.190.2053.0	25.194.3453.0	25.320.4853.1	25.320.5253.1	25.326.3253.1	25.326.3553.1	25.330.1653.1
25.330.4753.1	25.330.5253.1	25.334.3253.1	25.334.3353.1	25.350.2053.0	25.352.4753.1	25.522.3253.0	<u>T483C</u> <u>T484C</u>	<u>T485F</u> <u>T485H</u>
T512F-YEB	<u>T513F</u> <u>T514F</u> <u>T</u>	T554 T612FSE	25.161.3453.0	25.179.2253.0	25.194.3253.0	25.325.1253.1	25.326.4253.1	25.330.0953.1
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